FIG. 1

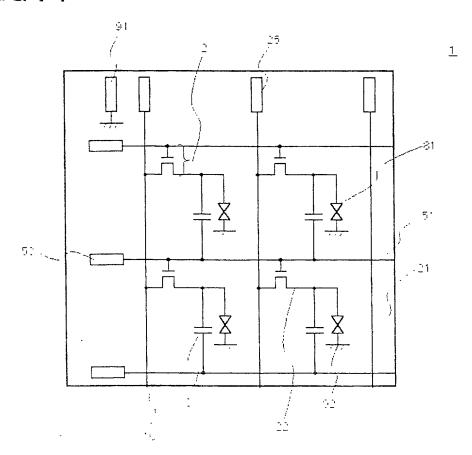


FIG . 2

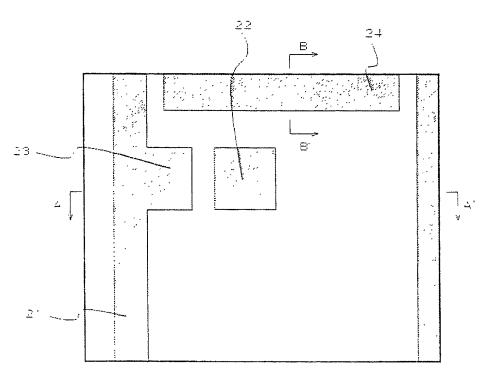


FIG.3

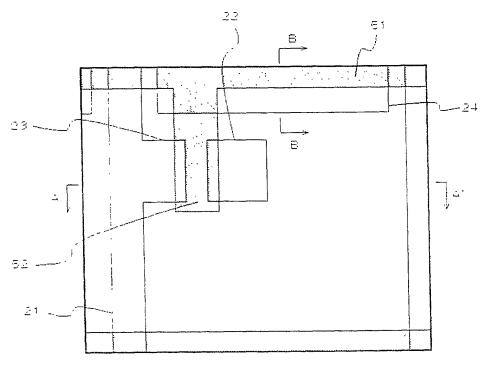


FIG. 4

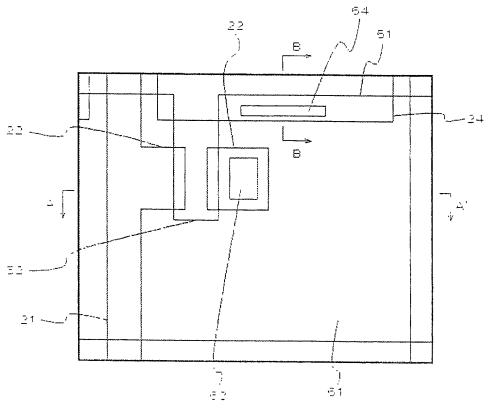


FIG . 5

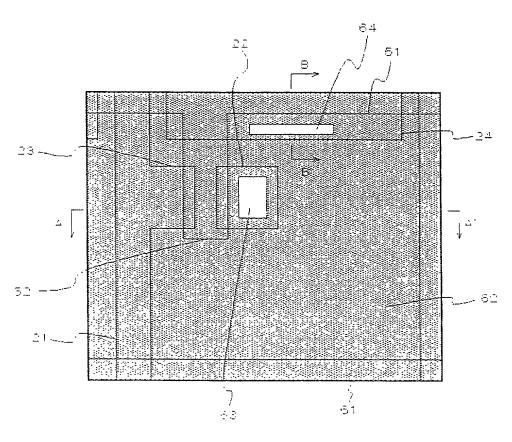
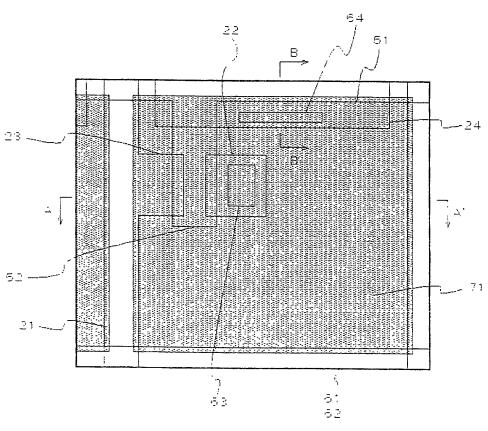
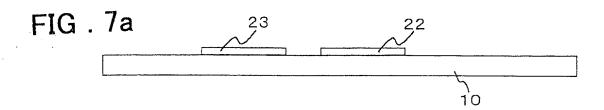
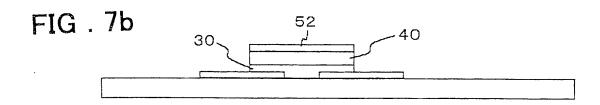
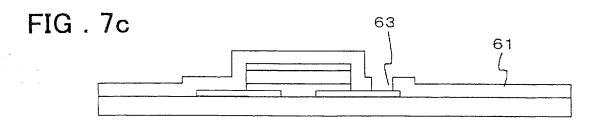


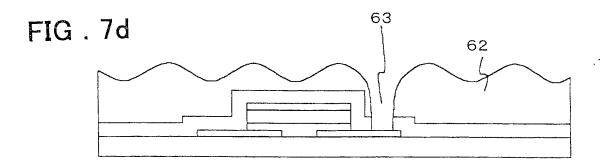
FIG. 6

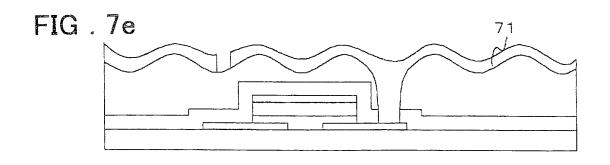




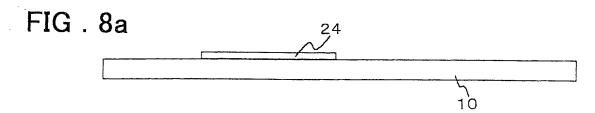


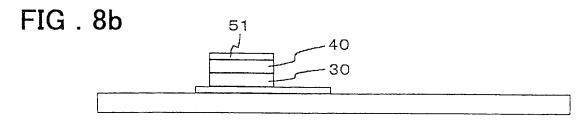


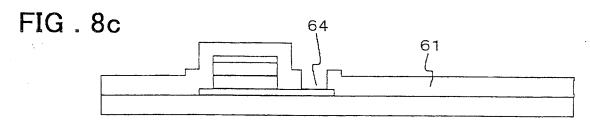


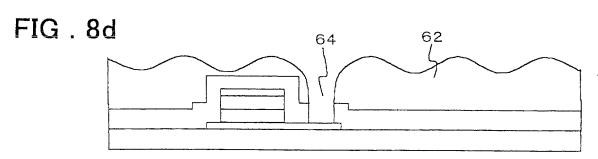












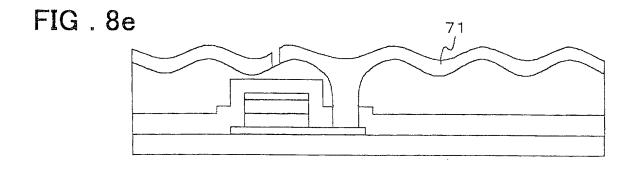
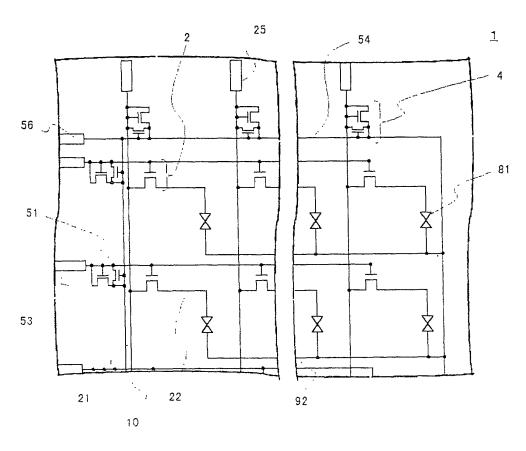


FIG . 9



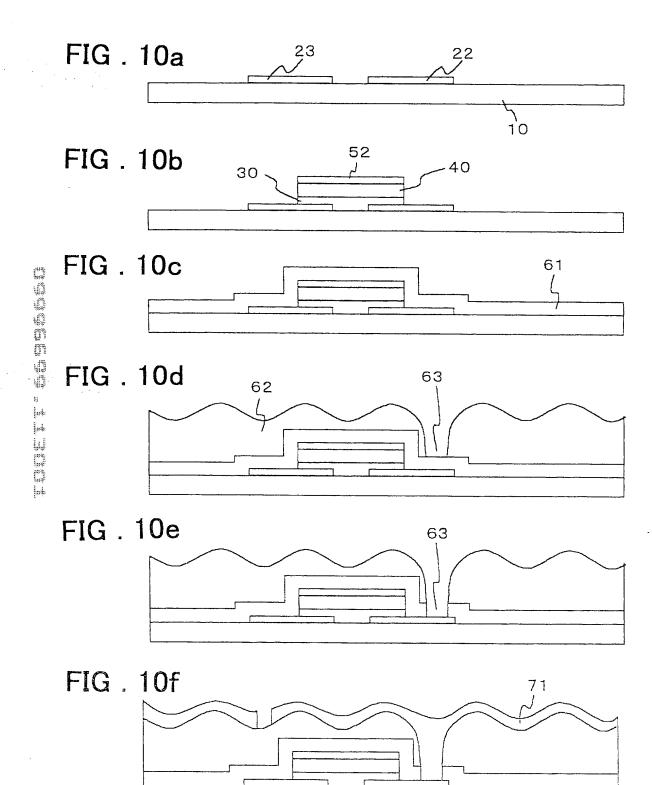


FIG . 11

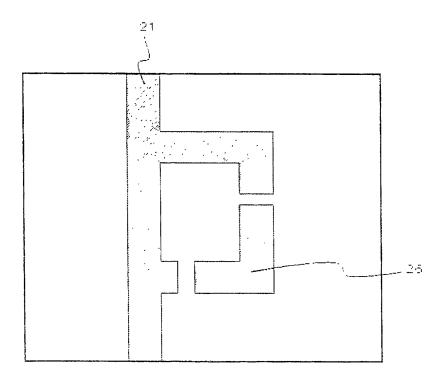


FIG . 12

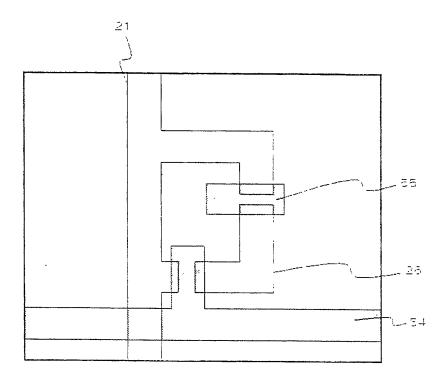


FIG . 13

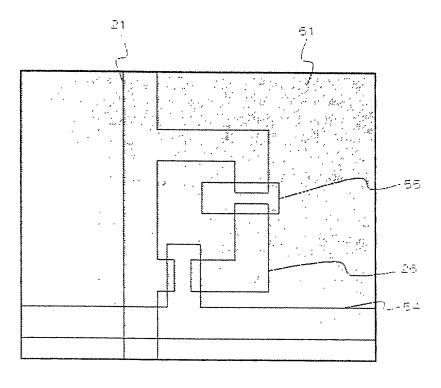


FIG .14

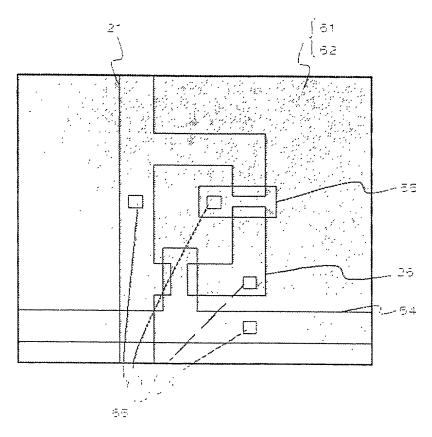


FIG .15

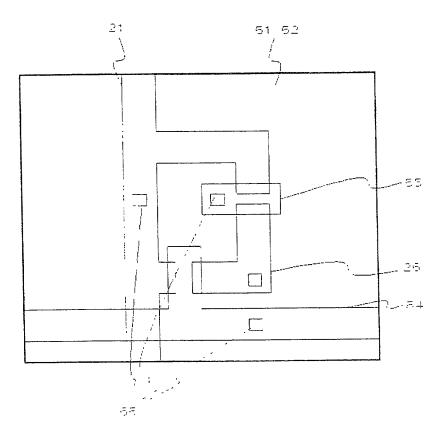
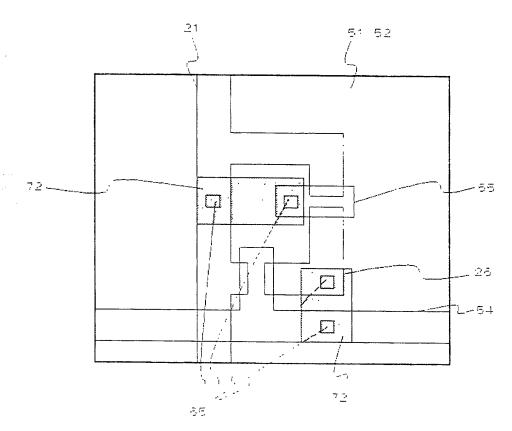
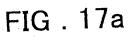


FIG . 16





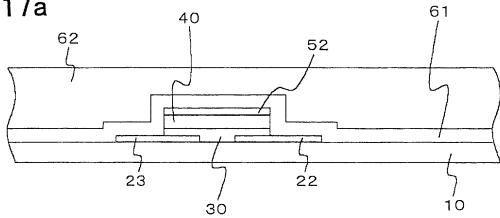


FIG . 17b

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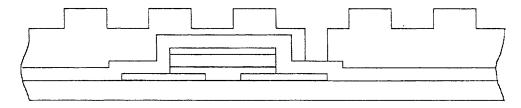


FIG . 17c

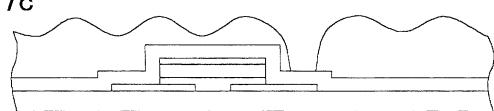
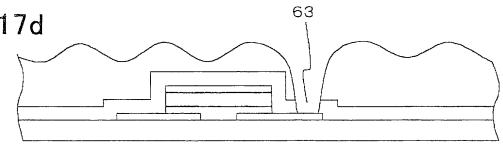


FIG . 17d



GATE BUS WIRING AND GATE ELECTRODE ARE FORMED	s1
GATE INSULATING FILM IS FORMED	s2
CONTACT LAYER AND SEMICONDUCTOR LAYER ARE FORMED	s3
SOURCE ELECTRODE, DRAIN ELECTRODE AND SOURCE BUS WIRING ARE FORMED	s4
INSULATING FILM IS FORMED	s5
CONTACT HOLE IS FORMED	s6
PHOTOSENSITIVE ORGANIC FILM IS APPLIED	s7
CONVEX IS FORMED	s8
REFLECTION ELECTRODE IS FORMED	s9